

5th International Conference on Electronic Packaging Technology



ICEPT 2003

Oct. 28-30, 2003 Shanghai, China
Sofitel Jin Jiang Oriental ★★★★★



We invite you to come to Shanghai, the center of electronics in China. The conference keynote talks and sessions have over 70 technical presentations, covering advanced electronics packaging technologies, modeling and simulation, manufacturing processes, bonding and soldering, materials, reliability and testing, MEMS and SMT, and more. For a full program, please review our Advanced Program on the website. Spouse program available. Early registration deadline: **27 September 2003**.

Keynote Speakers (partial listing):

Prof. Rao Tummala, PRC, Georgia Tech

Prof. Michael Pecht, CALCE Ctr, Univ of Maryland

Prof. Shen-Li Fu, President, I-Shou University

Robert C. Pfahl, NEMI

Prof. C.P. Wong, PRC, Georgia Tech

Prof. Tadatomo Suga, University of Tokyo

Dr. Kouchi (G.Q.) Zhang, Eindhoven University

Charles E. Bauer, TechLead Corp

Seyong Oh, Samsung Electronics

Mahadevan Iyer, Singapore IME.

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Organized by: Fudan Univ. (China) **Co-organized by:** Asian Information Inc. (China)

Conference Registration:

Linggen Song: lgsong@fudan.ac.cn or Fax: 86-21-65103056

Exhibition Registration:

Ding Li: asianinfo@online.sh.cn or Fax: 86-21-64697155 **by Sep.27, 2003**

For further information please visit the conference home page: <http://www.icept2003.org>

If you cannot attend, the Proceedings will be available through IEEE: www.cpmt.org/proceedings/